A Good Standard Cell Library

Cell libraries determine the overall performance of the synthesized logic

Synthesis engines rely on a number of factors for optimization The cell library should be designed catered solely towards the synthesis approach

Here are some guidelines:

A variety of drive strengths for all cells

Larger varieties of drive strengths for inverters and buffers

Cells with balanced rise and fall delays (for clock tree buffers/gated clocks)

Same logical function and its inversion as separate outputs, within same cell

Complex cells (e.g. AOI, OAI)

High fanin cells

- A Good Standard Cell Library
 - Variety of flip-flops, both positive and negative edge triggered, preferably with multiple drive strengths
 - Single or Multiple outputs available for each flip-flop (e.g. Q only, or Qbar only or both), preferably with multiple drive strengths
 - Flops to contain different inputs for Set and Reset (e.g. Set only, Reset only, both)
 - Variety of latches, both positive and negative level sensitive
 - Several delay cells. Useful for fixing hold time violations
 - To enable scan testing of the designs, each flip-flop should have an equivalent scan flop

Using high fan-in reduce the overall cell area, but may cause routing congestion inadvertently causing timing degradation. Therefore they should be used with caution

Standard Cell Library/Library Exchange Format (LEF)

Library Exchange Format (LEF)

An ASCII data format from Cadence, used to describe a standard cell library

Includes the design rules for routing and the Abstract Layout of the cells, no information about the internal netlist of the cells

A LEF file contains the following sections:

- Technology: layer, design rules, via definitions, metal capacitance
- Site: Site extension
- Macros: cell descriptions, cell dimensions, layout of pins and blockages, capacitances.

The technology is described by the Layer and Via statements. To each layer the following attributes may be associated:

- type: Layer type can be routing, cut (contact), masterslice (poly, active), overlap.
- width/pitch/spacing rules

direction

- resistance and capacitance per unit square
- antenna Factor

Standard Cell Library/Library Exchange Format (LEF) **Advanced VLSI Design CMPE 414** Library Exchange Format (LEF) Layers are defined in process order from bottom to top poly masterslice cc cut metal1 routing via cut metal2 routing via2 cut metal3 routing Cut Layer definition LAYER *layername* TYPE CUT; SPACING Specifies the minimum spacing allowed between via cuts on the same net or different nets. This value can be overridden by the SAMENET SPACING statement (we are going to use this statement later) END *layerName*

Standard Cell Library/Library Exchange Format (LEF)

Library Exchange Format (LEF)

Implant Layer definition

LAYER layerName

TYPE IMPLANT;

SPACING minSpacing

END *layerName*

Defines implant layers in the design. Each layer is defined by assigning it a name and simple spacing and width rules. These spacing and width rules only affect the legal cell placements.

These rules interact with the library methodology, detailed placement, and filler cell support.

Masterslice or Overlap Layer definition

LAYER layerName

TYPE {MASTERSLICE | OVERLAP};

Defines masterslice (nonrouting) or overlap layers in the design. Masterslice layers are typically polysilicon layers and are only needed if the cell MACROs have pins on the polysilicon layer.



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Routing Layer definition LAYER layerName TYPE ROUTING ; DIRECTION {HORIZONTAL | VERTICAL} ; PITCH distance; WIDTH defWidth; OFFSET distance ; SPACING minSpacing; RESISTANCE RPERSQ value ;

Specifies the resistance for a square of wire, in ohms per square.

The resistance of a wire can be defined as RPERSQU x wire length/wire width

CAPACITANCE CPERSQDIST value;

Specifies the capacitance for each square unit, in picofarads per square micron. This is used to model wire-to-ground capacitance.



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Library Exchange Format (LEF)

Manufacturing Grid

MANUFACTURINGGRID value;

Defines the manufacturing grid for the design. The manufacturing grid is used for geometry alignment. When specified, shapes and cells are placed in locations that snap to the manufacturing grid.

Via

```
VIA viaName
DEFAULT
TOPOFSTACKONLY
FOREIGN foreignCellName [pt [orient]] ;
RESISTANCE value ;
{LAYER layerName ;
{RECT pt pt ;} ...} ...
END viaName
```

Defines vias for usage by signal routers. Default vias have exactly three layers used: a cut layer, and two layers that touch the cut layer (routing or masterslice). The cut layer rectangle must be between the two routing or masterslice layer rectangles.

Standard Cell Library/Library Exchange Format (LEF)

Library Exchange Format (LEF)

Via Rule Generate VIARULE viaRuleName GENERATE LAYER routingLayerName; { DIRECTION {HORIZONTAL | VERTICAL }; **OVERHANG** overhang; METALOVERHANG metalOverhang; | ENCLOSURE overhang1 overhang2;} LAYER routingLayerName; { DIRECTION {HORIZONTAL | VERTICAL }; OVERHANG overhang; METALOVERHANG metalOverhang; | ENCLOSURE overhang1 overhang2;} LAYER cutLayerName; RECT *pt pt* ; SPACING xSpacing BY ySpacing; **RESISTANCE** resistancePerCut ; END viaRuleName

Defines formulas for generating via arrays. Use the VIARULE GENERATE statement to cover special wiring that is not explicitly defined in the VIARULE statement.

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Library Exchange Format (LEF)

Same-Net Spacing

SPACING

SAMENET *layerName layerName minSpace* **[STACK]** ; ...

END SPACING

Defines the same-net spacing rules. Same-net spacing rules determine minimum spacing between geometries in the same net and are only required if same-net spacing is smaller than different-net spacing, or if vias on different layers have special stacking rules.

Thesespecifications are used for design rule checking by the routing and verification tools.

Spacing is the edge-to-edge separation, both orthogonal and diagonal.

Site

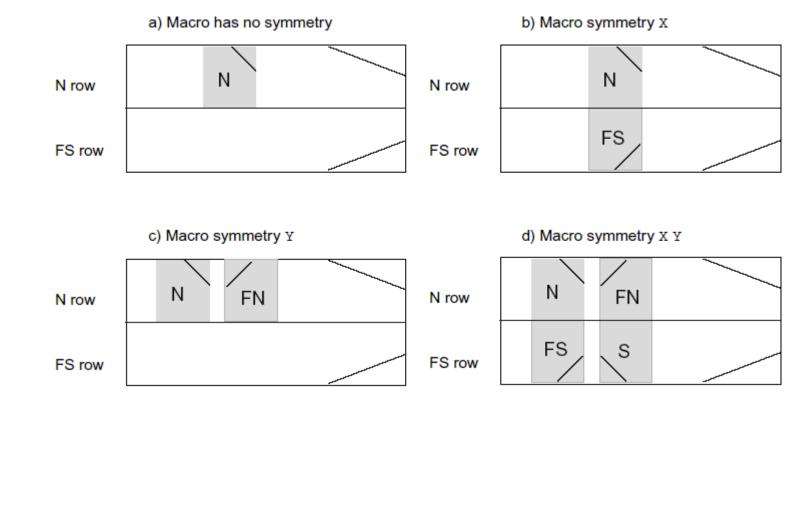
SITE siteName
CLASS {PAD | CORE};
[SYMMETRY {X | Y | R90} ...;] (will discuss this later in macro definition)
SIZE width BY height;
END siteName

```
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Library Exchange Format (LEF)
     Macro
     MACRO macroName
     [CLASS]
     { COVER [BUMP]
     RING
     BLOCK [BLACKBOX]
     PAD [INPUT | OUTPUT | INOUT | POWER | SPACER | AREAIO]
     CORE [FEEDTHRU | TIEHIGH | TIELOW | SPACER | ANTENNACELL]
      ENDCAP {PRE | POST | TOPLEFT | TOPRIGHT | BOTTOMLEFT | BOTTOMRIGHT }
     [SOURCE {USER | BLOCK};]
     [FOREIGN foreignCellName [pt [orient]];] ...
     [ORIGIN pt ;]
     [SIZE width BY height ;]
     [SYMMETRY {X | Y | R90} ... ;]
     [SITE siteName ;]
     [PIN statement] ...
     [OBS statement] ...
```

Standard Cell Library/Library Exchange Format (LEF)

Library Exchange Format (LEF)

Defining Symmetry



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Library Exchange Format (LEF)
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Macro Pin Statement
```

```
PIN pinName
FOREIGN foreignPinName [STRUCTURE [pt [orient]]];
[DIRECTION {INPUT | OUTPUT [TRISTATE] | INOUT | FEEDTHRU};]
[USE { SIGNAL | ANALOG | POWER | GROUND | CLOCK };]
[SHAPE {ABUTMENT | RING | FEEDTHRU};]
[MUSTJOIN pinName ;]
{PORT
[CLASS {NONE | CORE} ;]
{layerGeometries} ...
END} ...
END pinName]
```

```
Macro Obstruction Statement
```

OBS

```
{ LAYER layerName [SPACING minSpacing | DESIGNRULEWIDTH value] ;
RECT pt pt ;
POLYGON pt pt pt pt ... ;
END
```